

# **N-Channel Super Junction Power MOSFET**

### **General Description**

The series of devices use advanced super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

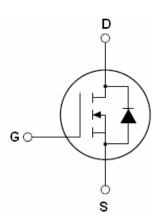
#### **Features**

- New technology for high voltage device
- ●Low on-resistance and low conduction losses
- Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ●ROHS compliant

### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

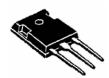
V <sub>DS</sub> @T <sub>jmax</sub>	560	V
R <sub>DS(ON)</sub>	190	mΩ
I <sub>D</sub>	20	A



Schematic diagram

### Package Marking And Ordering Information

Device	Device Package	Marking
NCE20N50T	TO-247	NCE20N50T



TO-247

Table 1. Absolute Maximum Ratings ( $T_c=25^{\circ}$ C)

Parameter	Symbol	NCE20N50T	Unit
Drain-Source Voltage (V <sub>GS=0</sub> V)	V <sub>DS</sub>	500	V
Gate-Source Voltage (VDS=0V)	V <sub>G</sub> S	±30	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	20	Α
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	12.5	Α
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	60	Α
Drain Source voltage slope, VDS = 400 V, ID = 20 A, Tj =	dv/dt	50	V/ns
125 °C	dv/dt	30	V/IIS
Maximum Power Dissipation(Tc=25℃)	$P_D$	208	W
Derate above 25°C		1.67	W/°C
Single pulse avalanche energy (Note 2)	Eas	690	mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AR</sub>	20	Α
Repetitive Avalanche energy , $t_{\text{AR}}$ limited by $T_{\text{jmax}}$ (Note 1)	E <sub>AR</sub>	1	mJ



Parameter	Symbol	NCE20N50T	Unit
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55+150	°C

<sup>\*</sup> limited by maximum junction temperature

### **Table 2. Thermal Characteristic**

Parameter	Symbol	NCE20N50T	Unit
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	0.6	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	$R_{thJA}$	62	°C /W

Table 3. Electrical Characteristics (TA=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states			U .		l .	l
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	500			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =500V,V <sub>GS</sub> =0V		0.05	1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =500V,V <sub>GS</sub> =0V			100	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	2.5	3	3.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A		155	190	mΩ
Dynamic Characteristics						
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> = 20V, I <sub>D</sub> = 10A		17.5		S
Input Capacitance	C <sub>lss</sub>	\/ -50\/\/ -0\/		2400		pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V,		180		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz		5.7		pF
Total Gate Charge	$Q_g$	\/ -400\/   -204		59		nC
Gate-Source Charge	$Q_{gs}$	V <sub>DS</sub> =400V,I <sub>D</sub> =20A,		10		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		26		nC
Intrinsic gate resistance	$R_G$	f = 1 MHz open drain		0.9		Ω
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			10		nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =380V, $I_{D}$ =20A,		5		nS
Turn-Off Delay Time	$t_{d(off)}$	$R_G=3.6\Omega, V_{GS}=10V$		67	100	nS
Turn-Off Fall Time	t <sub>f</sub>			4	12	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T -25°C			20	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			60	Α
Forward on voltage	$V_{SD}$	Tj=25°C,I <sub>SD</sub> =20A,V <sub>GS</sub> =0V		0.9	1.3	V
Reverse Recovery Time	t <sub>rr</sub>			360		nS
Reverse Recovery Charge	Q <sub>rr</sub>	Tj=25°C,I <sub>F</sub> =20A,di/dt=100A/μs		5.5		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>			30		Α

 $Notes\ 1. \\ \textit{Repetitive Rating: Pulse width limited by maximum junction temperature}$ 

<sup>2.</sup> Tj=25°C,VDD=50V,VG=10V, R<sub>G</sub>=25 $\Omega$ 



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area for NCE20N50T

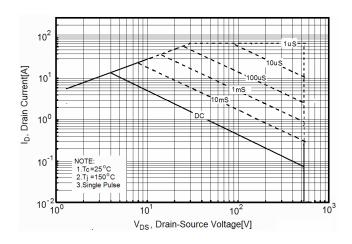


Figure 2. Source-Drain Diode Forward Voltage

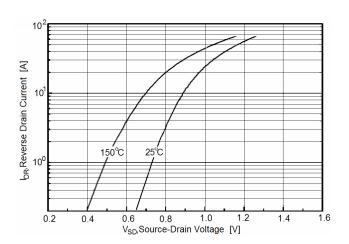


Figure 3. Output characteristics

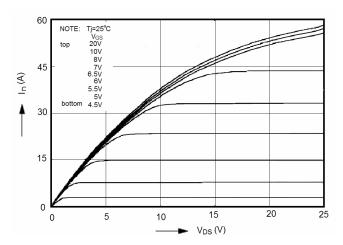


Figure 4. Transfer characteristics

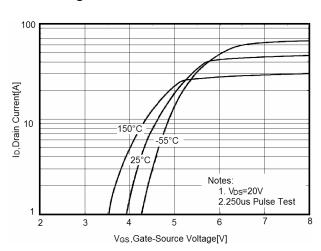


Figure 5. Static drain-source on resistance

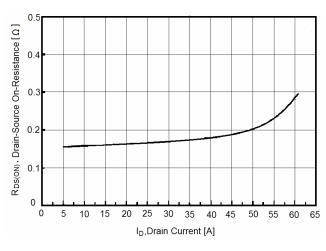


Figure 6. R<sub>DS(ON)</sub> vs Junction Temperature

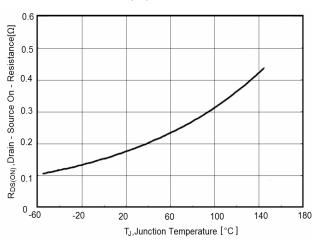




Figure 7. BV<sub>DSS</sub> vs Junction Temperature

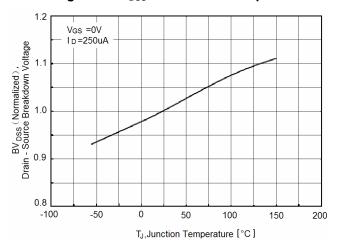


Figure 8. Maximum  $I_{\text{D}}$  vs Junction Temperature

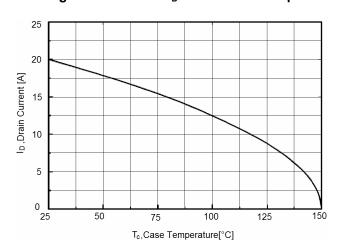


Figure 9. Gate charge waveforms

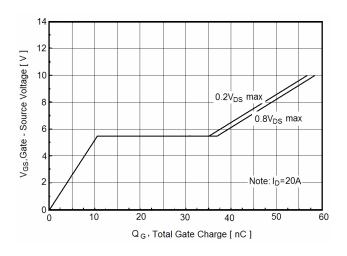


Figure 10. Capacitance

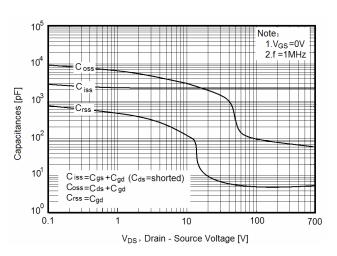
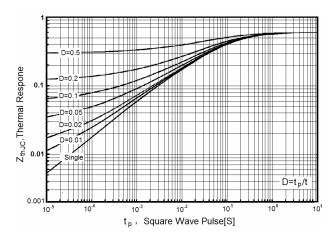


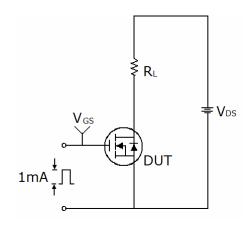
Figure 11. Transient Thermal Impedance

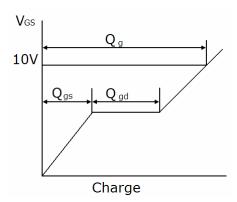




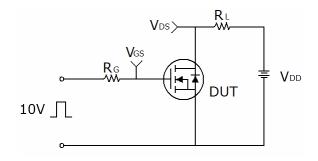
# **Test circuit**

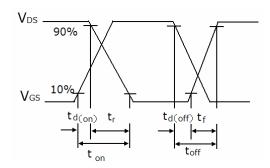
### 1) Gate charge test circuit & Waveform



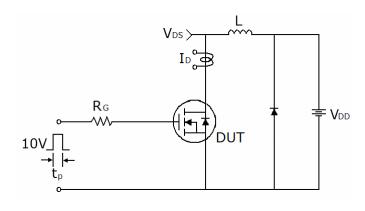


### 2) Switch Time Test Circuit:

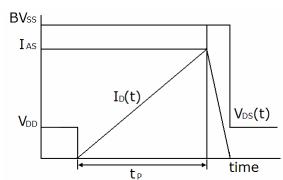




## 3) Unclamped Inductive Switching Test Circuit & Waveforms

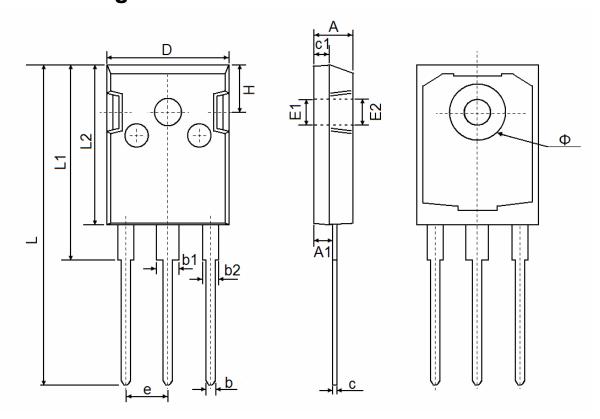


Wuxi NCE Power Semiconductor Co., Ltd





# **TO-247 Package Information**



Comple of	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
А	4.850	5.150	0.191	0.200		
A1	2.200	2.600	0.087	0.102		
b	1.000	1.400	0.039	0.055		
b1	2.800	3.200	0.110	0.126		
b2	1.800	2.200	2.200 0.071			
С	0.500	0.700 0.020		0.028		
c1	1.900	2.100	0.075	0.083		
D	15.450	15.750	0.608	0.620		
E1	3.500	) REF	0.138 REF			
E2	3.600	) REF	0.142	REF		
L	40.900	41.300	1.610	1.626		
L1	24.800	25.100	0.976	0.988		
L2	20.300	20.600	0.799	0.811		
Ф	7.100	7.300	0.280	0.287		
е	5.450	5.450 TYP		TYP		
Н	5.980	5.980 REF		5.980 REF 0.235 REF		REF



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